

描述 / Descriptions

超快恢复二极管，反向电压：1000V，正向电流：4.0A，SMBF 封装。

Surface Mount Ultrafast Recovery Rectifier, Reverse Voltage: 1000V, Forward Current: 4.0A, SMBF package.

特征 / Features

玻璃钝化芯片，效率高，无铅符合欧盟 RoHS 指令 2011/65/EU，适用于表面贴装。无卤产品。

Glass Passivated Chip Junction, High efficiency, Lead free in comply with EU R0HS 2011/65/EU directives, For surface mounted applications. Halogen free product.

用途 / Applications

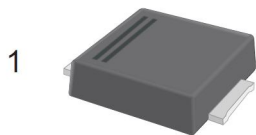
一般用途。

General purpose.

内部等效电路 / Equivalent Circuit



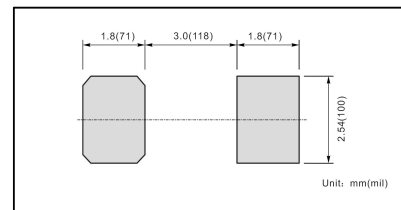
引脚排列 / Pinning



2

PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	参数符号 Symbol	数值 Rating	单位 Unit
		RS4MBF	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current at $T_c = 100^\circ\text{C}$	$I_{F(AV)}$	4.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	100	A
Typical Junction Capacitance at $V_R=4\text{V}$, $f=1\text{MHz}$	C_j	40	pF
Typical Thermal Resistance ⁽¹⁾	$R_{\theta JA}$	40	°C/W
	$R_{\theta JC}$	12	
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150	°C

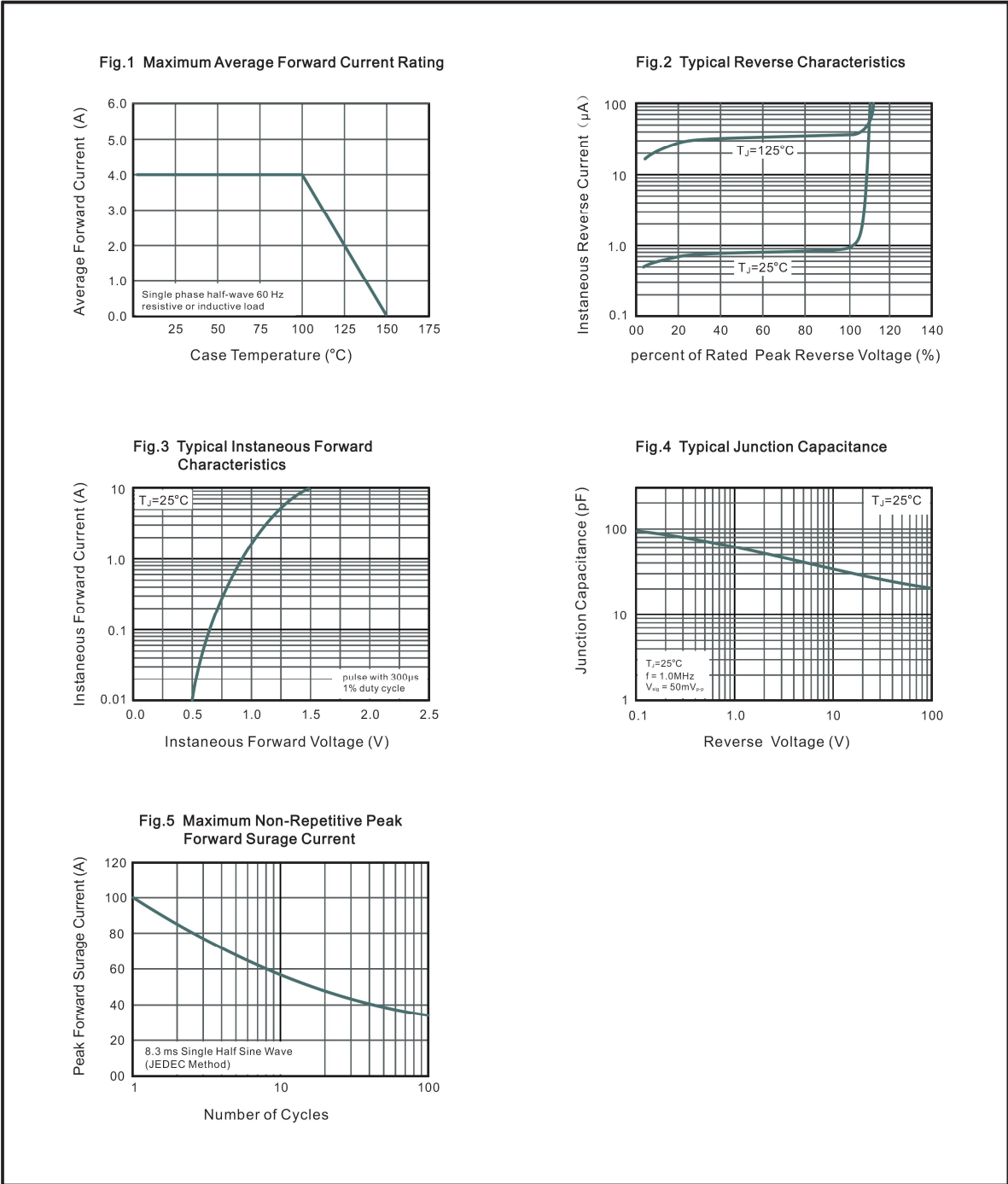
Note:

(1) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

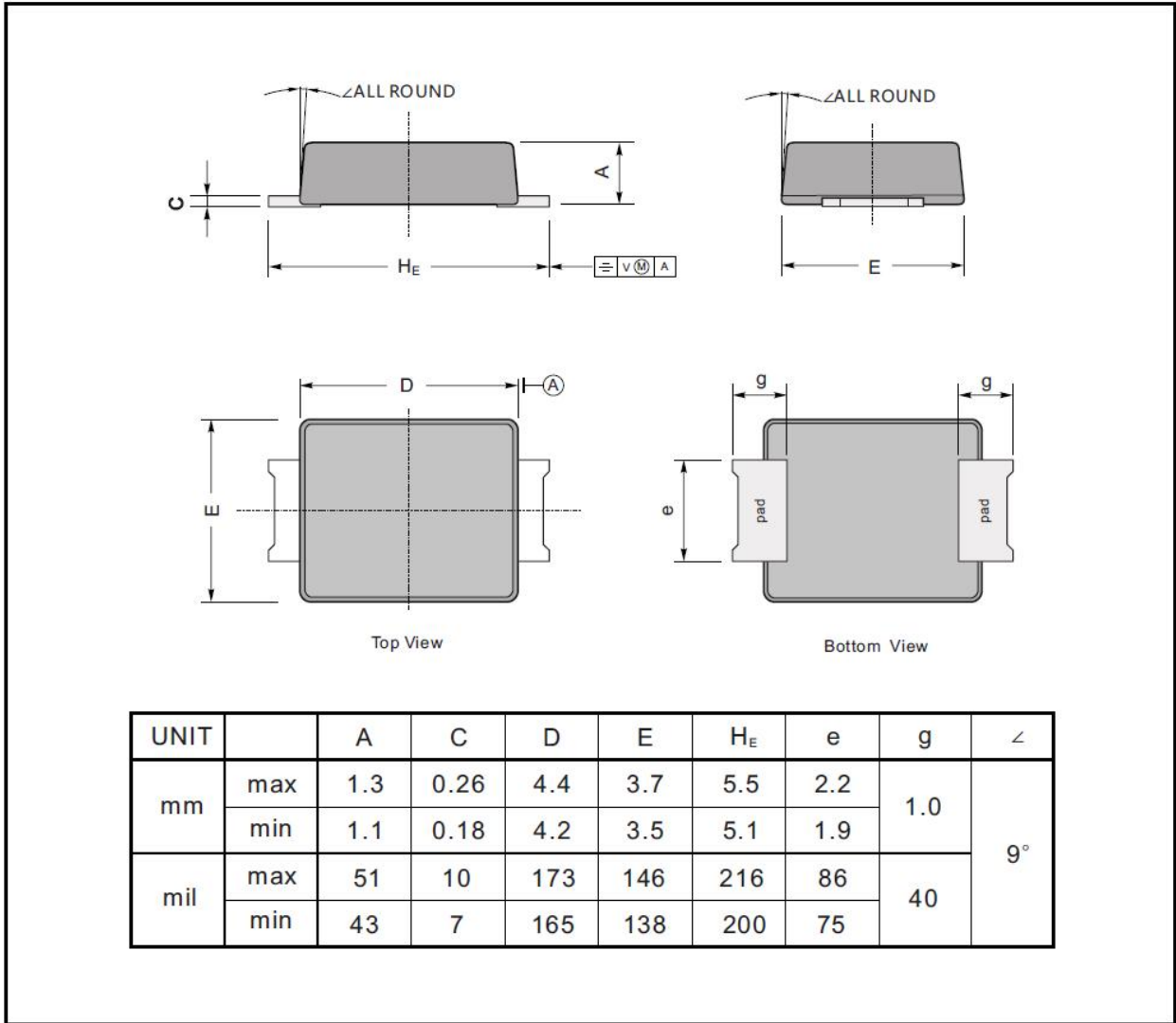
参数 Parameter	参数符号 Symbol	测试条件 Test condition	数值 Rating	单位 Unit
			RS4MBF	
Maximum Instantaneous Forward Voltage	V_F	$I_F=4.0\text{A}$	1.3	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25^\circ\text{C}$	10	uA
		$T_a=125^\circ\text{C}$	150	
Maximum Reverse Recovery Time	T_{rr}	$I_F=0.5\text{A}$ $I_R=1.0\text{A}$ $I_{rr}=0.25\text{A}$	500	ns

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

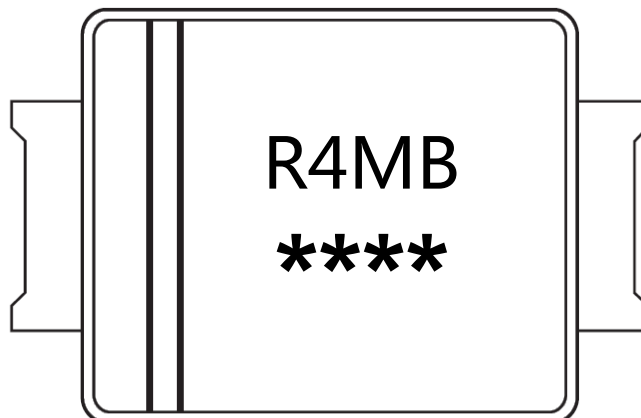
SMBF



Marking

Type number	Marking code
RS4MBF	R4MB

印章说明 / Marking Instructions



说明：

R4MB：为型号代码

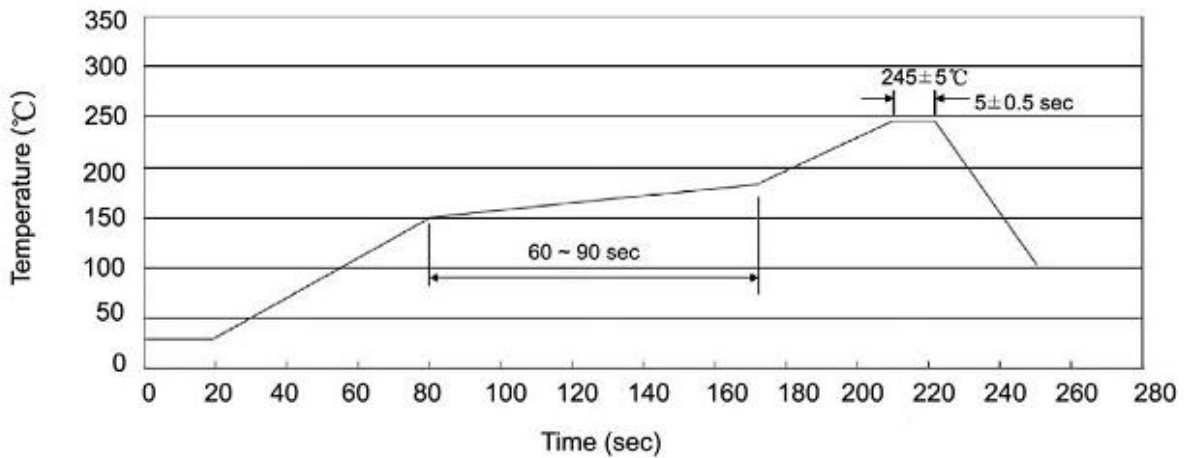
****：为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

R4MB：Product Type Code

****：Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMBF	5000	2	10000	7	50000	13" ×12	336X332X40	345X345X235

使用说明 / Notices